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(54) **SYSTEMS AND METHODS FOR
MANUFACTURING PRINTED CIRCUIT
BOARDS**

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ABSTRACT

Systems and methods for overcoming technical problems associated with machining and manufacturing printed circuit boards. In some embodiments, the systems and methods include a process to remove or reduce defects in initially created printed circuit board (PCB) traces. For example, a method can include a process to remove or reduce burrs of laser micromachined PCB traces (which can be electrically isolated from each other). In some cases, a material is deposited over the PCB traces, and the depositing results in a conducting layer that electrically connects all or most of the PCB traces and provides an electrical connection for removing or reducing the defects in the PCB traces.

